

# High Power Multi-Junction Pulsed Laser Diodes 905D1S3J0XSMD

## Features

- Multi-junction devices up to 70 W
- 75  $\mu\text{m}$ , 150  $\mu\text{m}$ , and 225  $\mu\text{m}$  source size
- Proven InGaAs / GaAs high reliability structure
- High power multi-junction structure for narrow far field
- Excellent temperature stability
- Reflow solderable surface mount package
- Top or side-looking

## Applications

- LIDAR
- Range finding
- Surveying equipment
- Obstacle detection
- Medical

## Optical Characteristics at $t_{RT} = 21^\circ\text{C}$ , $I_{FM}$

	Min	Typ	Max	Units
Wavelength of peak radiant intensity $\lambda$	895	905	915	nm
Spectral bandwidth $\Delta\lambda$ at 50% intensity points		8		nm
Wavelength temperature coefficient		0.27		nm/ $^\circ\text{C}$
Beam spread (50% peak intensity)				
Parallel to junction plane $\parallel$		10		Degrees
Perpendicular to junction plane $\perp$		23		Degrees

Optical Characteristics at  $t_{RT} = 21^\circ\text{C}$ , 30 A, 100 ns, 1 kHz

Parameter	905D1S3J09SMD
$P_O$ at 30 A (typ.)	70 W
Emitting area	235 x 10 $\mu\text{m}$
$I_{TH}$ typ	750 mA
$I_{TYP}$ at 100 ns	30 A
Forward voltage at $I_{MAX}$ (typ.)	8.5 V

## Absolute Maximum Ratings

Maximum ratings	Limiting values
Peak reverse voltage	6 V
Pulse duration	150 ns
Duty factor	0.1%
Temperature	
- Storage	-55 °C to + 100 °C
- Operating	-45 °C to + 85 °C
Max. soldering temperature	235 °C (see figure 5)

Figure 1:  
Output power vs. forward current

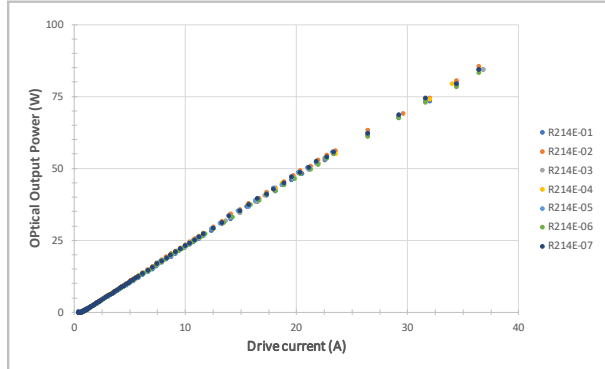


Figure 2:  
Spectral intensity distribution

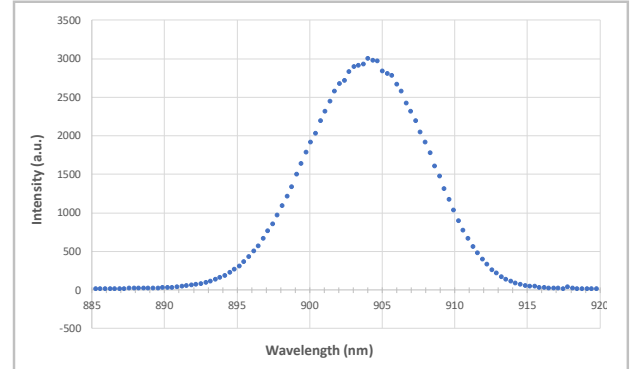


Figure 3:  
Near field beam profile

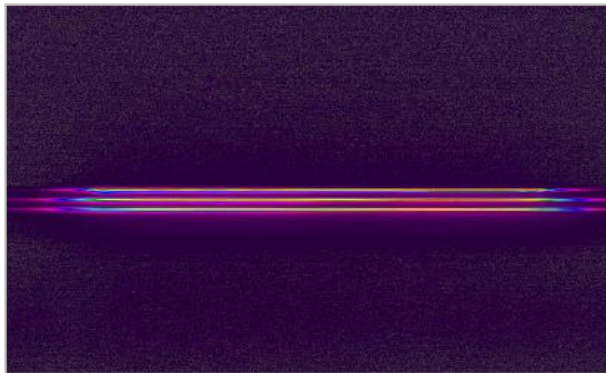


Figure 4:  
Far field beam profile

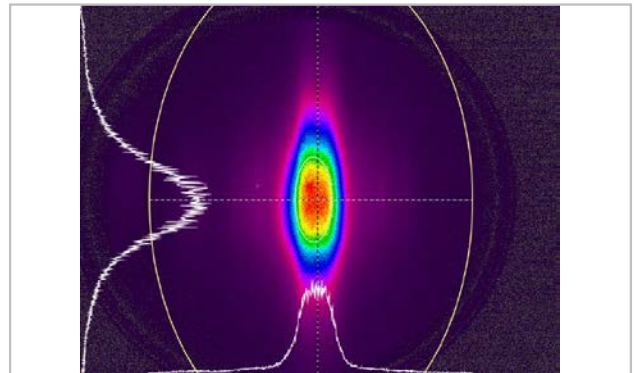
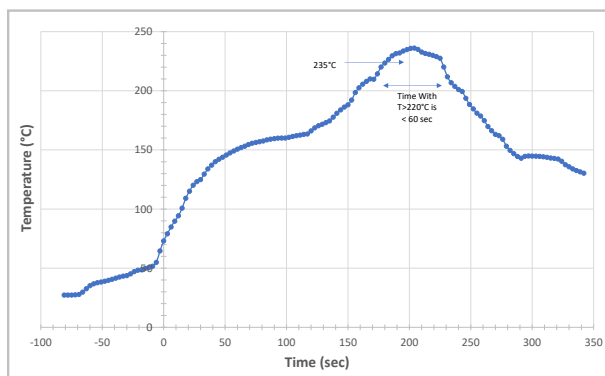


Figure 5:  
Typical recommended soldering reflow profile

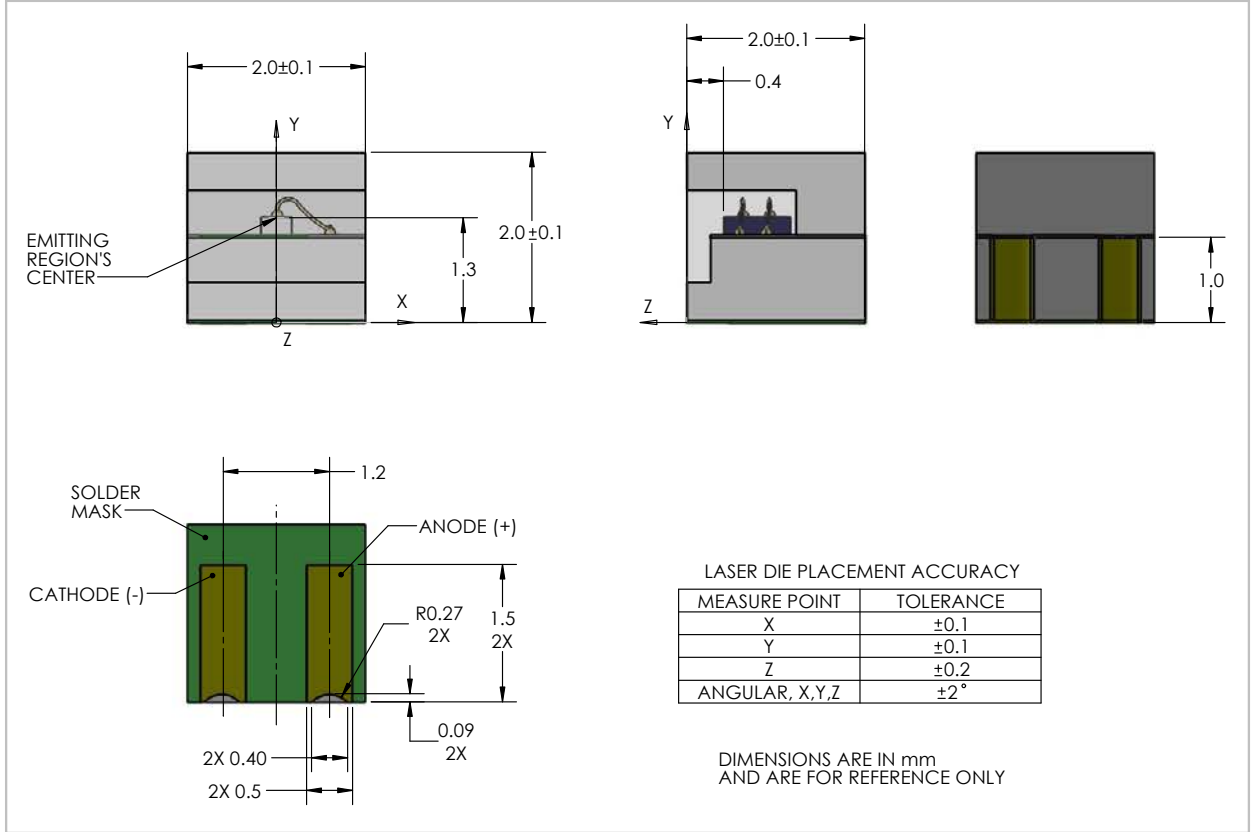


**Note:**

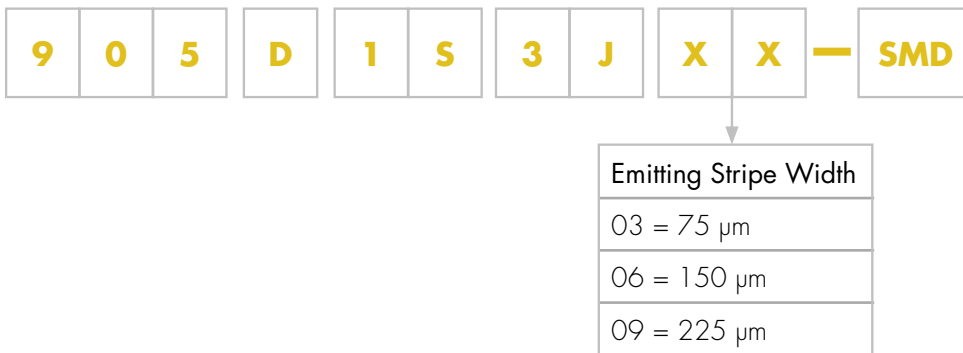
Reflow oven profile must follow J-STD-020 JEDEC Standard with the following recommendations:

- Max. temperature must not exceed 235 °C
- Time with T > 220 °C must not exceed one minute

Figure 6:  
Package drawing



## Product Number Designations



## Product Changes

LASER COMPONENTS reserves the right to make changes to the product(s) or information contained herein without notice. No liability is assumed as a result of their use or application.

## Ordering Information

Products can be ordered directly from LASER COMPONENTS or its representatives. For a complete listing of representatives, visit our website at [www.lasercomponents.com](http://www.lasercomponents.com)

Custom designed products are available on request.

## Laser Safety

### Personal Hazard:

Depending on the mode of operation, these devices emit highly concentrated non visible infrared light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1 "Safety of laser products".

### Handling Precautions:

Products are subject to the risks normally associated with sensitive electronic devices including static discharge, transients, and overload.

